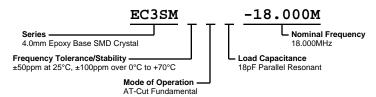
EC3SM-18.000M

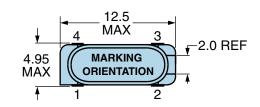


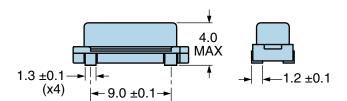


| ELECTRICAL SPECIFICATIONS | | |
|-------------------------------|---|--|
| Nominal Frequency | 18.000MHz | |
| Frequency Tolerance/Stability | ±50ppm at 25°C, ±100ppm over 0°C to +70°C | |
| Aging at 25°C | ±5ppm/year Maximum | |
| Load Capacitance | 18pF Parallel Resonant | |
| Shunt Capacitance (C0) | 7pF Maximum | |
| Equivalent Series Resistance | 50 Ohms Maximum | |
| Mode of Operation | AT-Cut Fundamental | |
| Drive Level | 1mWatts Maximum | |
| Storage Temperature Range | -40°C to +85°C | |
| Insulation Resistance | 500 Megaohms Minimum at 100Vdc | |

| ENVIRONMENTAL & MECHANICAL SPECIFICATIONS | | |
|---|--------------------------------------|--|
| Fine Leak Test | MIL-STD-883, Method 1014 Condition A | |
| Gross Leak Test | MIL-STD-883, Method 1014 Condition C | |
| Mechanical Shock | MIL-STD-202, Method 213 Condition C | |
| Resistance to Soldering Heat | MIL-STD-202, Method 210 | |
| Resistance to Solvents | MIL-STD-202, Method 215 | |
| Solderability | MIL-STD-883, Method 2003 | |
| Temperature Cycling | MIL-STD-883, Method 1010 | |
| Vibration | MIL-STD-883, Method 2007 Condition A | |

MECHANICAL DIMENSIONS (all dimensions in millimeters)





| PIN | CONNECTION |
|-----|--------------------|
| 1 | Crystal |
| 2 | Connected to Pin 3 |
| 3 | Connected to Pin 2 |
| 4 | Crystal |

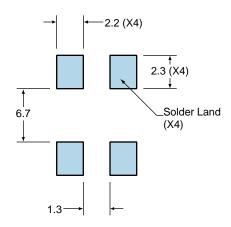
| LINE | MARKING |
|------|----------------------------------|
| 1 | E18.000 E=Ecliptek Designator |

EC3SM-18.000M



Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ±0.1

EC3SM-18.000M



Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 225°C

| T _s MAX to T _L (Ramp-up Rate) | 5°C/second Maximum |
|---|----------------------------|
| Preheat | |
| - Temperature Minimum (T _s MIN) | N/A |
| - Temperature Typical (T _s TYP) | 150°C |
| - Temperature Maximum (T _s MAX) | N/A |
| - Time (t _s MIN) | 30 - 60 Seconds |
| Ramp-up Rate (T _L to T _P) | 5°C/second Maximum |
| Time Maintained Above: | |
| - Temperature (T∟) | 150°C |
| - Time (t∟) | 200 Seconds Maximum |
| Peak Temperature (T _P) | 225°C Maximum |
| Target Peak Temperature (T _P Target) | 225°C Maximum 2 Times |
| Time within 5°C of actual peak (tp) | 80 seconds Maximum 2 Times |
| Ramp-down Rate | 5°C/second Maximum |
| Time 25°C to Peak Temperature (t) | N/A |
| Moisture Sensitivity Level | Level 1 |

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.